



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL31C180JBCNNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 18pF, 50V, ±5%, C0G, 1206

A. Samsung Part Number

<u>CL</u> <u>31</u> <u>C</u> <u>180</u> <u>J</u> <u>B</u> <u>C</u> <u>N</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

| 1 | Series | Samsung Multi-layer Ceramic Capacitor | | |
|-----|---------------|---------------------------------------|-------------------|-------------------------|
| 2 | Size | 1206 (inch code) | L: 3.2 ± 0.15 mm | W: 1.6 ± 0.15 mm |
| | | | | |
| 3 | Dielectric | C0G | 8 Inner electrode | Ni |
| 4 | Capacitance | 18 pF | Termination | Cu |
| (5) | Capacitance | ±5 % | Plating | Sn 100% (Pb Free) |
| | tolerance | | 9 Product | Normal |
| 6 | Rated Voltage | 50 V | Special | Reserved for future use |
| 7 | Thickness | 0.85 ± 0.15 mm | ① Packaging | Cardboard Type, 7" reel |

B. Samsung Reliablility Test and Judgement condition

| | Performance | Test condition | |
|------------------------------|--|--------------------------------------|--|
| Capacitance | Within specified tolerance | 1Mb±10% 0.5~5Vrms | |
| Q | 760 min | | |
| Insulation | 10,000Mohm or 500Mohm⋅ <i>μ</i> F | Rated Voltage 60~120 sec. | |
| Resistance | Whichever is Smaller | | |
| Appearance | No abnormal exterior appearance | Microscope (×10) | |
| Withstanding | No dielectric breakdown or | 300% of the rated voltage | |
| Voltage mechanical breakdown | | | |
| Temperature C0G | | | |
| Characterisitcs | (From -55 $^{\circ}\!$ | | |
| Adhesive Strength | No peeling shall be occur on the | 500g·F, for 10±1 sec. | |
| of Termination | terminal electrode | | |
| Bending Strength | Capacitance change : | Bending to the limit (1mm) | |
| | within ±5% or ±0.5pF whichever is larger | with 1.0mm/sec. | |
| Solderability | More than 75% of terminal surface | SnAg3.0Cu0.5 solder | |
| | is to be soldered newly | 245±5℃, 3±0.3sec. | |
| | | (preheating : 80~120℃ for 10~30sec.) | |
| | | | |
| Resistance to | Capacitance change : | Solder pot : 270±5℃, 10±1sec. | |
| Soldering heat | within ±2.5% or ±0.25pF whichever is larger | | |
| | Tan δ, IR : initial spec. | | |

| | Performance | Test condition |
|---|---|--|
| Vibration Test Capacitance change : | | Amplitude : 1.5mm |
| | within ±2.5% or ±0.25pF whichever is larger | From 10Hz to 55Hz (return : 1min.) |
| | Tan δ, IR : initial spec. | 2hours \times 3 direction (x, y, z) |
| Moisture | Capacitance change : | With rated voltage |
| Resistance within ±7.5% or ±0.75pF whichever is large | | 40±2℃, 90~95%RH, 500+12/-0hrs |
| | Q: 160 min | |
| | IR: 500Mohm or 25Mohm $\cdot \mu$ F | |
| | Whichever is Smaller | |
| High Temperature | Capacitance change : | With 200% of the rated voltage |
| Resistance | within ±3% or ±0.3pF whichever is larger | Max. operating temperature |
| | Q: 320 min | 1000+48/-0hrs |
| | IR : 1000Mohm or 50Mohm $\cdot \mu$ F | |
| | Whichever is Smaller | |
| Temperature | Capacitance change : | 1 cycle condition |
| Cycling | within ±2.5% or ±0.25pF whichever is larger | Min. operating temperatur → 25 °C |
| | Tan δ, IR : initial spec. | $ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}\!$ |
| | | |
| | | |
| | | 5 cycle test |

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C, 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.